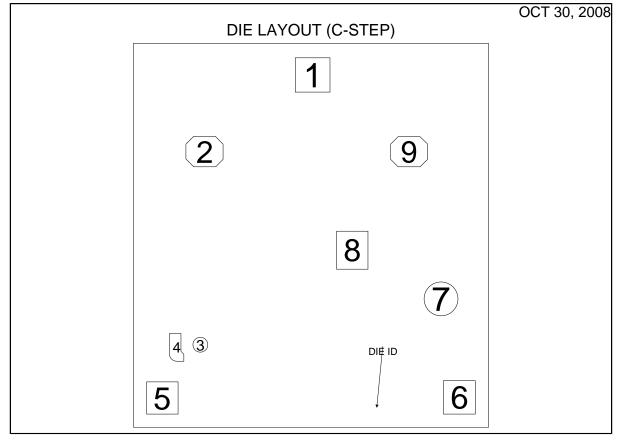


LM117H MDR MCD2680A SMD#5962R9951703V9A 3-TERMINAL ADJUSTABLE REGULATOR



## **DIE/WAFER CHARACTERISTICS**

Fabrication Attributes		General Die Information		
Physical Die	117C	Bond Pad Opening	193.04µm x 198.12µm	
Identification		Size (min)		
Die Step	С	Bond Pad Metalization	AL 0.5%CU	
Physical Attributes		Passivation	VOM ONLY	
Wafer Diameter	150mm	Back Side Metal	Gold	
Die Size (Drawn)	2184.40µm x 2362.20µm	Back Side Connection	Output	
	86.0mils x 93.0mils			
Thickness	254µm Nominal			
Min Pitch	1827.53µm			
Note: All values are round	ded to the nearest micron.			
Special Assembly Requirements:				



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Die Bond Pad Coordinate Locations(C-Step) (Referenced to die center, coordinates in $\mu$ m) NC = No Connection, N.U. = Not Used						
Signal Name	Pad Number X/Y Coordinates		ordinates	Pad Size		
•		Х	Y	Х		Y
Input	1	10	987	213	Х	211
Output	2	-655	516	229	х	188
NC	3	-681	-673	91	Х	91
NC	4	-827	-690	89	х	17(
Output	5	-914	-1001	193	х	198
Adj	6	913	-997	196	х	206
NC	7	800	-391	208	х	208
Input	8	254	-91	193	х	234
Output	9	603	514	226	х	18



DPBU Die Datasheet

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